

1 CLAIMS

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- 3 1. A circuit board assembly comprising;
- 4 a planar circuit board having a major surface and a side surface,
- 5 a planar substrate mounted on the major surface of the circuit board, an
- 6 extended portion of the planar substrate extending beyond the side surface, and
- 7 an optical transceiver module mounted on the extended portion of the
- 8 substrate adjacent the side surface of the printed circuit board.
- 9
- 10 2. An assembly as claimed in claim 1, wherein the planar circuit board
- 11 includes an end portion defining a recess in which the optical transceiver module
- 12 is disposed.
- 13
- 14 3. An assembly as claimed in claim 1, wherein the planar substrate includes
- 15 electrically conductive interconnects for coupling electrical terminals on the optical
- 16 transceiver module with electrical terminals on the planar circuit board.
- 17
- 18 4. An assembly as claimed in claim 1, wherein the planar substrate and the
- 19 planar circuit board are substantially parallel.
- 20
- 21 5. An assembly as claimed in claim 1, wherein the planar substrate is soldered
- 22 onto the major surface of the planar circuit board.
- 23
- 24 6. An assembly as claimed in claim 1, wherein the optical transceiver module
- 25 is soldered onto the extended portion of the planar substrate.
- 26
- 27 7. An assembly as claimed in claim 1, wherein the optical transceiver module
- 28 is mounted on, and the major surface of the planar circuit board faces a same side
- 29 of the planar substrate.
- 30
- 31
- 32 8. A method of manufacturing a circuit board assembly comprising:
- 33 providing a planar substrate,

1 mounting an optical transceiver module on a first portion of the
 2 planar substrate, and
 3 mounting a second portion of the planar substrate on a major surface of a
 4 circuit board such that the optical transceiver module is disposed adjacent a side
 5 surface of the planar circuit board.

6 *page 9, line 25 = 27, cutting*
 7 9. A method as claimed in claim 8, further comprising:
 8 singularising the planar substrate from a relatively larger planar substrate.

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 10 10. A circuit board assembly comprising;
 11 a planar circuit board having a major surface, and a side surface defining a
 12 recess,
 13 a planar substrate mounted on the major surface of the circuit board, an
 14 extended portion of the planar substrate extending over the recess, and
 15 an optical transceiver module mounted on the extended portion of the
 16 substrate so as to be disposed in the recess.

17 *257/99*
 18 11. An optical transceiver module package for mounting on a planar circuit
 19 board having a major surface and a side surface, the major surface provided with
 20 electrical terminals, the optical transceiver module package comprising:
 21 a planar substrate for mounting on the major surface of the circuit board so
 22 that an extended portion of the planar substrate extends beyond the side surface,
 23 an optical transceiver module provided with electrical terminals and
 24 mounted on the extended portion of the substrate adjacent the side surface of the
 25 printed circuit board, and
 26 electrically conductive interconnects associated with the planar substrate
 27 for coupling the electrical terminals on the optical transceiver module with
 28 electrical terminals on the planar circuit board.

29
 30 12. An optical transceiver module package for mounting on a planar circuit
 31 board having a major surface and at least one side surface defining a recess, the
 32 major surface provided with electrical terminals, the optical transceiver module
 33 package comprising:

4 an optical transceiver module provided with electrical terminals and
5 mounted on the extended portion of the substrate so as to be disposed in the
6 recess, and

electr